# DC-DC Converter (-20V, -3.0A)

# RTL030P02

#### Features

- 1) Low on-resistance. ( $80m\Omega$  at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

# Applications

DC-DC converter

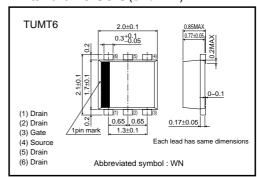
#### Structure

Silicon P-channel MOS FET

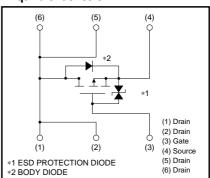
### Packaging specifications

|           | Package                      | Taping |  |
|-----------|------------------------------|--------|--|
| Type      | Code                         | TR     |  |
|           | Basic ordering unit (pieces) | 3000   |  |
| RTL030P02 |                              | 0      |  |

#### ●External dimensions (Unit : mm)



#### ●Equivalent circuit



# ●Absolute maximum ratings (Ta=25°C)

|                              | Symbol                   | Limits  | Unit   |
|------------------------------|--------------------------|---|--|
|                              | VDSS                     | -20   | V  |
|                              | $V_{GSS}$                | ±12   | V  |
| Continuous                   | $I_D$                    | ±3  | Α  |
| Pulsed                       | I <sub>DP</sub>          | ±12   | A *1   |
| Continuous                   | Is                       | -0.8  | A *1   |
| Pulsed                       | I <sub>SP</sub>          | -12   | Α  |
| Total power dissipation      |                          | 1   | W *2   |
| Channel temperature          |                          | 150   | °C   |
| Range of Storage temperature |                          | -55 to +150   | °C   |
|                              | Pulsed Continuous Pulsed | Voss Voss Voss Continuous Ib Pulsed IDP Continuous Is Pulsed Isp Po Tch | VDSS         -20           VGSS         ±12           Continuous         Ib         ±3           Pulsed         IbP         ±12           Continuous         Is         -0.8           Pulsed         IsP         -12           PD         1           Tch         150 |

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

# ●Electrical characteristics (Ta=25°C)

| Parameter                               | Symbol                | Min. | Тур. | Max. | Unit | Conditions  |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage                     | I <sub>GSS</sub>      | -    | -    | ±10  | μΑ   | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V        |
| Drain-source breakdown voltage          | V <sub>(BR)</sub> DSS | -20  | -    | _    | V    | I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V        |
| Zero gate voltage drain current         | IDSS                  | _    | -    | -1   | μΑ   | Vps= -20V, Vgs=0V                                 |
| Gate threshold voltage                  | VGS (th)              | -0.7 | -    | -2.0 | V    | Vps= -10V, Ip= -1mA                               |
| Static drain-source on-state resistance |                       | _    | 50   | 70   | mΩ   | I <sub>D</sub> = -3.0A, V <sub>GS</sub> = -4.5V * |
|   | R <sub>DS (on)</sub>  | -    | 55   | 77   | mΩ   | I <sub>D</sub> = -3.0A, V <sub>GS</sub> = -4V *   |
|   |                       | -    | 90   | 125  | mΩ   | I <sub>D</sub> = -1.5A, V <sub>GS</sub> = -2.5V * |
| Forward transfer admittance             | Yfs                   | 2.0  | -    | _    | S    | V <sub>DS</sub> = -10V, I <sub>D</sub> = -1.5A *  |
| Input capacitance                       | Ciss                  | -    | 760  | _    | pF   | V <sub>DS</sub> = -10V                            |
| Output capacitance                      | Coss                  | -    | 125  | _    | pF   | V <sub>GS</sub> =0V                               |
| Reverse transfer capacitance            | Crss                  | -    | 100  | _    | pF   | f=1MHz  |
| Turn-on delay time                      | td (on)               | _    | 12   | _    | ns   | ID= -1.5A *                                       |
| Rise time                               | tr                    | _    | 25   | _    | ns   | VDD≒ -15V *                                       |
| Turn-off delay time                     | t <sub>d (off)</sub>  | _    | 50   | _    | ns   | $V_{GS} = -4.5V$ $R_{L} = 10\Omega$               |
| Fall time                               | t <sub>f</sub>        | _    | 22   | _    | ns   | RGS= $10\Omega$                                   |
| Total gate charge                       | Qg                    | _    | 8.0  | _    | nC   | V <sub>DD</sub> ≒−15V R <sub>L</sub> ≒5Ω          |
| Gate-source charge                      | Qgs                   | _    | 1.5  | _    | nC   | $V_{GS}=-4.5V$ RGS=10 $\Omega$                    |
| Gate-drain charge                       | Q <sub>gd</sub>       | _    | 2.5  | _    | nC   | I <sub>D</sub> =-3A                               |

Body diode characteristics (source-drain characteristics)

| body diode ondiaconomic (ocurse diam endiaconomics) |     |   |   |      |   |   |
|---|-----|---|---|------|---|---|
| Forward voltage                                     | VSD | _ | _ | -1.2 | V | I <sub>S</sub> = -0.8A, V <sub>GS</sub> =0V |

#### •Electrical characteristic curves

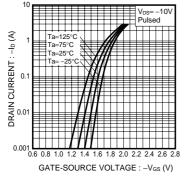


Fig.1 Typical Transfer Characteristics

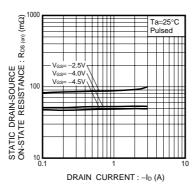


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

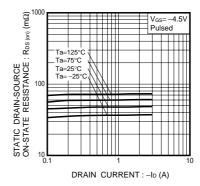


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

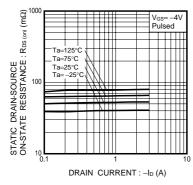


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

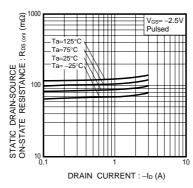


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

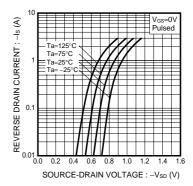


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

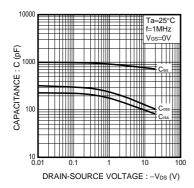


Fig.7 Typical Capacitance vs. Drain-Source Voltage

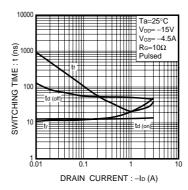


Fig.8 Switching Characteristics

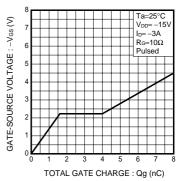


Fig.9 Dynamic Input Characteristics

#### ●Measurement circuits

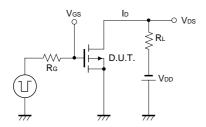


Fig.10 Switching Time Measurement Circuit

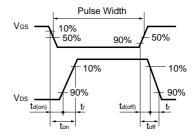


Fig.11 Switching Waveforms

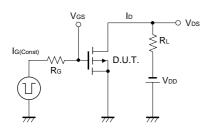


Fig.12 Gate Charge Measurement Circuit

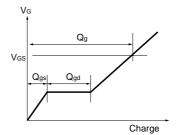


Fig.13 Gate Charge Waveforms

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